

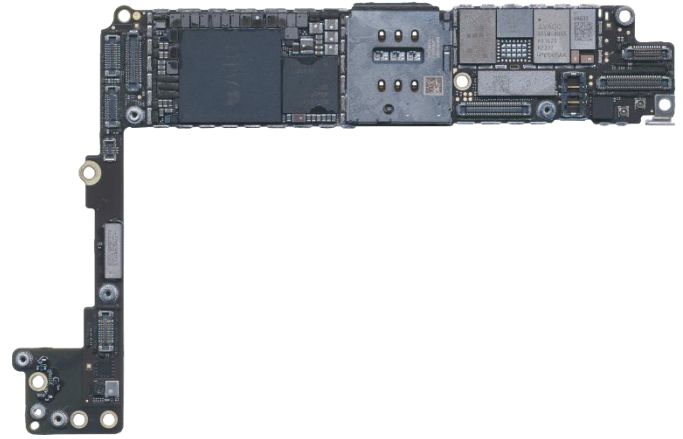
# Apple iPhone7 Plus A1661

www.sitrigroup.com

Weibo



Wechat



## Teardown Analysis Report

## Table Of Contents

### Teardown Analysis

Product Overview .....	Page 2
Packagings .....	Page 5
Exterior Features .....	Page 9
Major Components .....	Page 12
Teardown Sequence .....	Page 15
Switch .....	Page 19
Connector .....	Page 21
Electroacoustic .....	Page 23
Non-electronics .....	Page 25
Antenna .....	Page 26

### Subsystem Analysis

Battery .....	Page 31
Rear Camera .....	Page 33
Front Camera .....	Page 36
TP Information .....	Page 39

### Main Electronics Analysis

Non-electronics of Shields .....	Page 42
Shields Analysis .....	Page 44
PCB Board Analysis .....	Page 46
Connector Analysis .....	Page 51
Min Space Features .....	Page 56
Underfill Features .....	Page 58
IC Package Type Analysis .....	Page 60

www.sitrigroup.com

Weibo



Wechat



## Table Of Contents

IC Identification .....	Page 68
Sensor IC Overview .....	Page 77
Main Board Cross-Section .....	Page 93
Function Block .....	Page 94
FPC Analysis .....	Page 97

### Cost Analysis

Substrates .....	Page 101
IC Components .....	Page 102
Modular Components .....	Page 104
Discrete Components .....	Page 105
Connector Components .....	Page 107
Non-Electronic Cost Estimate .....	Page 108
Electronic Assembly Metrics .....	Page 109
Electronic Costs Breakdown .....	Page 113
Vendor IC Cost Distribution .....	Page 114
Cost Summary .....	Page 115
Final Ass'y Labor & Test Cost .....	Page 116

### Major Findings Analysis

Product Findings .....	Page 117
Sensor Findings .....	Page 118
Cost Findings .....	Page 119

www.sitrigroup.com

Weibo



Wechat

